

# A Miniaturized High-Voltage Solar Cell Array as an Electrostatic MEMS Power Supply

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**Abstract**—A hydrogenated amorphous silicon (a-Si:H) solar cell array that is designed as an on-board power source for electrostatic microelectromechanical systems (MEMS) is presented. A single cell consists of a triple layer of *p-i-n/p-i-n/p-i-n* a-Si:H and produces an open circuit voltage ( $V_{oc}$ ) of 1.8~2.3 V, a short circuit current density ( $J_{sc}$ ) of 2.8 mA/cm<sup>2</sup>, and fill factor (FF) of 0.495. A series interconnected array of 100 single solar cells (total array area of 1 cm<sup>2</sup>) is fabricated in an integrated fashion and produces an array  $V_{oc}$  of 150 V, and array short circuit current ( $I_{sc}$ ) of 2.8  $\mu$ A under Air Mass (AM) 1.5 illumination. To demonstrate the usefulness of this solar cell array as an on-board power source for electrostatically driven micromachined devices, it has been packaged with a movable micromachined silicon (Si) mirror in a hybrid manner. The movable Si mirror is directly driven by the cell array electrical output, and the motion of the mirror plate has been observed reproducibly. Variation of light intensity and/or number of illuminated cells produces different values of array  $V_{oc}$ , thus enabling control of the deflection of the Si mirror by variation of incident light intensity. [117]

## I. INTRODUCTION

SINCE THE power requirements of micromachined devices are usually quite different from those of general electrical circuitry, additional external power connections or voltage/current conversion circuitry are commonly used in microelectromechanical systems (MEMS). In many applications, these methods of power supply are not a problem; however, for autonomous operation, such as free-moving microbotic systems and space-based MEMS, a self-contained on-board or remote power supply is desirable. Previous work in this area includes a rechargeable lithium microbattery [1] that can be used as a self-contained on-board power supply; an energy coupling method using an external magnetic field to remotely induce voltages and currents on-chip [2]; and dielectric loss heating by means of a remote electric field alternating at high frequency [3]. Solar cells are also attractive as power sources for MEMS since they are easily integrated and, therefore, can be fabricated as a self-contained on-board power supply. In addition, solar cells are very well characterized and developed in many terrestrial, space, and commercial applications.

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However, to be used as power sources for MEMS, a suitable modification in the traditional design methodology of the solar cell is required to meet the power requirements of MEMS.

The power requirements of MEMS differ depending on the actuation principle involved. Common driving principles currently used for MEMS include electrostatic [4], magnetic [5], piezoelectric [6], and electrothermal [7] excitation. Typical power requirements of these driving principles are shown in Table I. Although some researchers have succeeded in decreasing the driving voltage of some electrostatic MEMS [8], these devices usually require driving voltages ranging from tens to hundreds of volts and driving currents in the nA~ $\mu$ A range. These voltages and currents are different from those traditionally available from solar cells, which are lower-voltage supplies. Thus, as discussed, a suitable modification in the traditional design is required. This paper consists of design criteria for solar cells as a power source for electrostatic MEMS, solar cell array fabrication, experimental results for a single cell, a series interconnected cell array, and an actuation demonstration using the cell array to drive a micromachined movable silicon (Si) mirror [9].

## II. PRINCIPLE OF OPERATION OF SOLAR CELL

A solar cell is a device producing electrical energy directly from light energy. The basic device requirement of a solar cell is an electronic asymmetry, such as a *p-n* junction. When illuminated, photogenerated electron-hole pairs (EHP) are generated throughout the solar cell. If the cell is connected to a load, current will flow from one region of the cell, through the load, and back to the other region of the cell. Fig. 1 shows an I-V characteristic curve for dark and illuminated conditions for a simple p-n junction. The  $I_{mp}$  and  $V_{mp}$  are the current and voltage operating point for maximum power output. An important solar cell parameter, the fill factor (FF), is defined as

$$FF = \frac{I_{mp}V_{mp}}{I_{sc}V_{oc}} \quad (1)$$

where  $I_{sc}$  is the short circuit current and  $V_{oc}$  is the open circuit voltage as defined in Fig. 1. The efficiency of a solar cell is defined as

$$\eta = \frac{I_{mp}V_{mp}}{P_{in}} = \frac{FF \cdot I_{sc} \cdot V_{oc}}{P_{in}} \quad (2)$$

where  $P_{in}$  is the input optical power to the solar cell.

TABLE I  
COMMON DRIVING PRINCIPLES IN MICROMACHINING AND THEIR POWER REQUIREMENTS

Device	Driving Principle	Material	Power Requirement	Reference
Motor	Electrostatic	poly-Si	60~400 V / nA ~ $\mu$ A	[4]
Motor	Magnetic	Ni-Fe	~ 1V / 500 mA	[5]
Motor	Piezoelectric	PZT	4V (100 kHz) / ~ $\mu$ A	[6]
Actuator	Electrothermal	Si/Au	~ 10 V / ~ mA	[7]

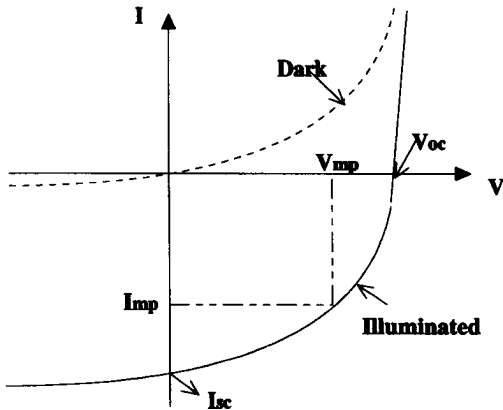


Fig. 1. I-V characteristic curve for a simple p-n junction under dark and illuminated conditions.

### III. DESIGN CRITERIA

Several design criteria for solar-cell-based MEMS power sources arise from the basic design rules of micromachining. First, the solar cell should consume as small an area as possible in order to minimize the overall size of the MEMS. Second, the solar cell should be electrically isolated from the substrate to allow an isolated integration of microsensors, microactuators, electrical circuitry, and the solar cell power supply. Third, the fabrication processes should be fully or partially compatible with each other. Additional design criteria arise from the power requirements of electrostatic MEMS. First, the individual cells must be able to be connected in series with each other so that the interconnected cell array can meet the high driving voltage requirement. Second, a high  $V_{oc}$  of a single cell is desirable. Note that in contrast to usual solar cell design criteria, maximization of the cell current and/or array current is not required since the typical driving current for electrostatic MEMS is in the nA~ $\mu$ A range. In order to facilitate series interconnection of cells, it is necessary to be able to make a connection from the bottom of one cell to the top of the next cell. Therefore, thin film solar cells may be preferred in order to meet this criterion. For the electrical isolation design, thin film solar cells are preferred once again since the electrical isolation of a thin film structure is much easier than a bulk wafer-type solar cell.

To make an efficient solar cell, it is necessary to provide for absorption of a large fraction of incident light, efficient collection of photogenerated EHP's, low internal series resistance, and low leakage current. These requirements are closely related to material properties. As the band gap decreases,  $J_{sc}$  increases because more photons can generate EHP's. The  $V_{oc}$ , however, decreases with decreasing band gap. Thus,

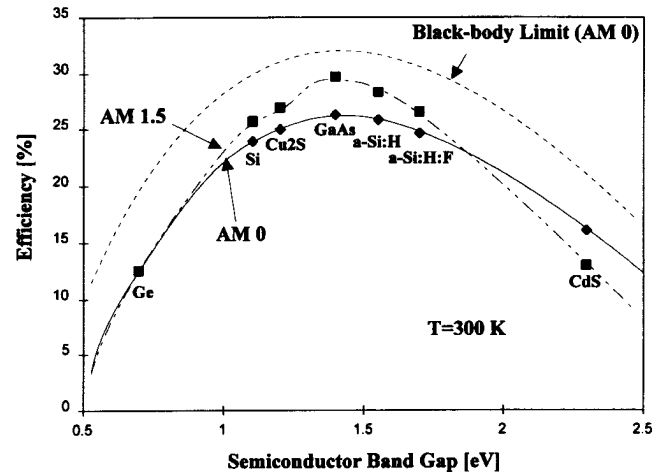


Fig. 2. Solar cell efficiency limits as a function of the band gap of the cell material [10].

there is an optimum band gap semiconductor for the highest efficiency. Fig. 2 [10] shows the solar cell efficiency limits for solar illumination for popular contemporary photovoltaic (PV) materials as a function of the band gap of the material. The peak efficiency occurs from 1.4 to 1.6 eV. Another important property in PV materials is the optical absorption coefficient  $\alpha(\lambda)$ , which is a function of the wavelength of the incident light. If the  $\alpha(\lambda)$  is high, a relatively thin structure is sufficient to absorb most of the incident light. This thin structure has the added advantage that a relatively short minority carrier diffusion length of the photogenerated EHP's is required for the minority carriers to reach the junction without recombination.

Table II shows output characteristics and typical thicknesses for various contemporary solar cells. Although the single crystal Si solar cell is the most common in PV technology and has a high  $J_{sc}$  and PV conversion efficiency, it has a relatively low  $\alpha(\lambda)$ . Thus, solar cells formed from this material have typical thickness of 200~400  $\mu$ m. Therefore, single crystal Si solar cells are usually formed in a bulk wafer, resulting in a failure to meet the design criteria discussed. The polycrystalline thin film Si solar cell has relatively low  $V_{oc}$ . Single-layer gallium arsenide (GaAs) and two terminal tandem GaAs solar cells have high  $V_{oc}$  in a single cell and can be realized as a thin film; however, GaAs is more expensive than the other materials. The cadmium telluride (CdTe)-based solar cells also have low  $V_{oc}$ . Taking into account several basic material properties, the hydrogenated amorphous silicon (a-Si:H) solar cell is a very attractive means to realize an on-board power supply for electrostatic MEMS for several

TABLE II  
TYPICAL PARAMETER SUMMARY OF THE MAJOR CONTEMPORARY SOLAR CELLS

Solar Cell	V <sub>oc</sub> [V]	J <sub>sc</sub> [mA/cm <sup>2</sup> ]	η [%]	Thickness [μm]	Reference
Single crystal Si	0.7	41	23	200 ~ 400	[11]
Thin film poly-Si	0.6	33	15.7	~ 30	[12]
GaAs	1.045	27.6	24.4	2 ~ 10	[13]
Two terminal tandem GaAs	2.403	13.96	27.6	2 ~ 10	[13]
Triple layer a-Si	2.541	6.96	12.4	~ 1	[13]
CdS/CdTe	0.446	31.1	8.1	~ 30	[14]

reasons. First, since it has a relatively large band gap (about 1.55 eV, depending on the hydrogen concentration), cells made from this material have a high  $V_{oc}$  of about 0.9 V. Second, the  $\alpha(\lambda)$  of a-Si:H is more than an order of magnitude larger than that of single crystal Si near the maximum solar photon energy region of 500 nm. Accordingly, the optimum thickness of the active layer in a-Si:H solar cells can be on the order of 1  $\mu\text{m}$ , much smaller than that of single crystal Si solar cells. Third, it is possible to stack multiple layers of a-Si:H to realize tandem cells for high voltage output and very efficient utilization of substrate area. Finally, since a-Si:H can be deposited using dc glow discharge decomposition and RF sputtering, it can be deposited on virtually any low cost substrate, thereby enabling cost-effective processing.

#### IV. A HYDROGENATED AMORPHOUS SILICON SOLAR CELL

Since Carlson and Wronski [15] reported the first a-Si:H solar cells, there have been tremendous efforts and improvements. The primary reason for the popularity of this material is the capability to fabricate devices at low cost. Due to the deposition technology which has been developed for a-Si:H solar cells, this material can be deposited virtually on any low cost substrate. In order to achieve high efficiency cells, multijunction-type a-Si solar cells have been proposed. Horizontally [16] and vertically [17] stacked multilayer solar cells have both been introduced in which a single cell has a  $V_{oc}$  in excess of 2 V. In theory, the larger the number of cells in a vertical stack, the larger the overall  $V_{oc}$  of the stack. However, in large number stacks, the thicknesses of the  $i$ -layers and the junction band gaps should be carefully designed [18] to achieve a high efficiency, so that the cells on the bottom of the stack contribute to the overall power generation. In this work, the vertically stacked triple junction cell has been investigated, since it is the most popular cell used in multijunction a-Si solar cells and therefore well characterized. These individual cell stacks are then interconnected horizontally in series to produce an array of high voltage output. The major disadvantage of a-Si as a material is the instability of the cell performance during the PV operation. Cells of a-Si exhibit degradation in performance after exposure to light, known as Staebler-Wronski effect [19]. In general, most of the degradation is observed in the first 48 hours of operation, and is accompanied by a drop in efficiency ( $\eta$ ) of 15 ~ 25%, due to a degradation of  $J_{sc}$  and FF [13]. However,  $V_{oc}$  is fairly stable [13], which is the most important criterion for electrostatic MEMS as the operating current is relatively low. There is a large

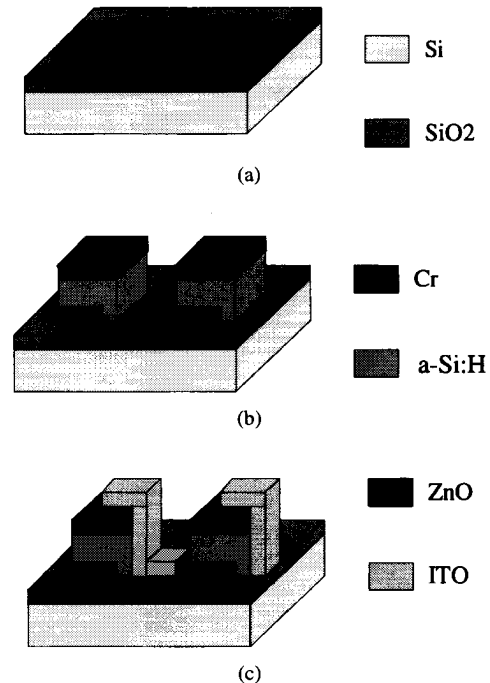


Fig. 3. The fabrication process of triple junction solar cell array. (a) Cr rear contact; (b) a-Si:H triple junction solar cell and anti-reflective coating; (c) ITO interconnection patterning (figures are not to scale).

literature on the long-term stability of a-Si-based solar cell [20], [21]. Another major issue of the a-Si:H solar cell in a MEMS application is the temperature limitation. The a-Si:H film begins to lose hydrogen at temperatures exceeding 400°C, irreversibly damaging the PV performance. Several MEMS fabrication processes do not exceed this temperature limit (such as electroplating-based processes [22], [23]); however, many of the common polycrystalline silicon processes will require the solar cell material to be deposited after the polysilicon deposition.

#### V. FABRICATION

A brief fabrication process of the solar cell array is shown in Fig. 3. The process begins with a 3-in.  $\langle 100 \rangle$  Si wafer as a substrate. A 4000 Å layer of silicon dioxide ( $\text{SiO}_2$ ) for electrical isolation is deposited onto the Si wafer by plasma enhanced chemical vapor deposition (PECVD) using silane ( $\text{SiH}_4$ ) and nitrous oxide ( $\text{N}_2\text{O}$ ). A 1- $\mu\text{m}$  layer of chromium (Cr) is deposited onto the  $\text{SiO}_2$  layer by dc sputtering. The Cr layer is patterned using 50% hydrochloric acid (HCl) to

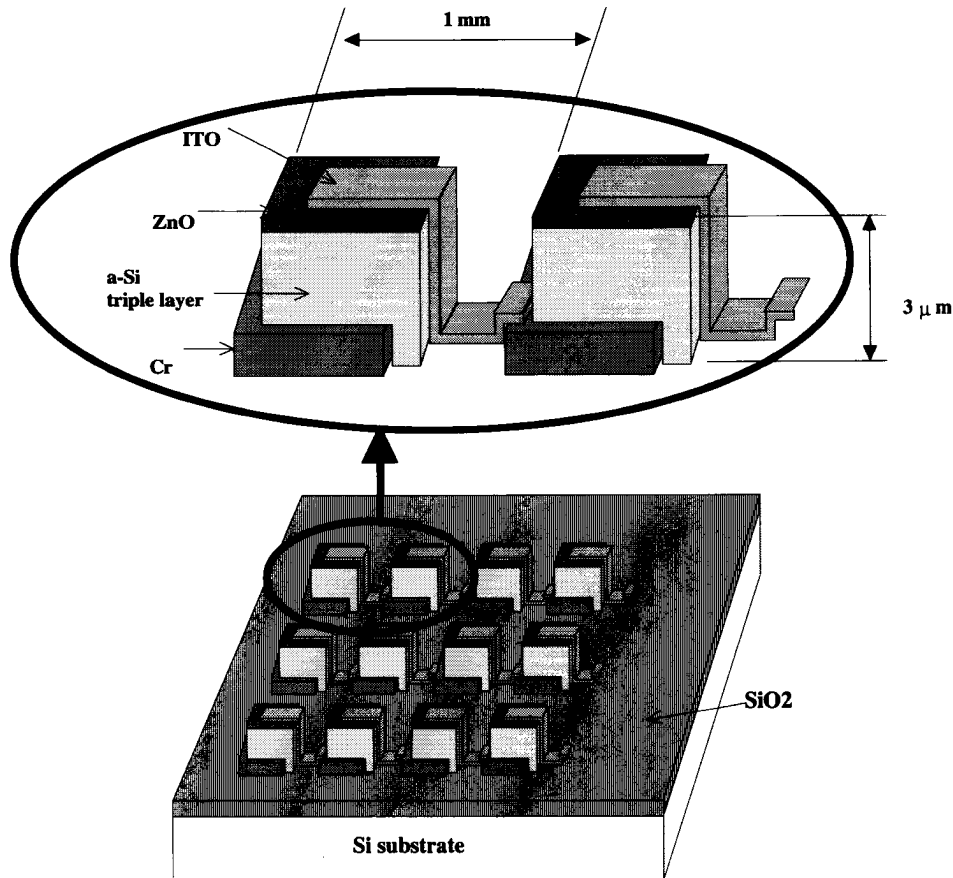


Fig. 4. The schematic diagram of series interconnected a-Si:H solar cell array.

form a rear contact. A total of  $1 \mu\text{m}$  of a-Si:H *p-i-n/p-i-n/p-i-n* triple junctions are deposited by dc glow-discharge decomposition of  $\text{SiH}_4$ , diborane ( $\text{B}_2\text{H}_6$ ), methane ( $\text{CH}_4$ ) for the *p*-layer,  $\text{SiH}_4$  for the *i*-layer, and  $\text{SiH}_4$ , phosphine ( $\text{PH}_3$ ) for the *n*-layer, respectively. A zinc oxide (ZnO) anti-reflective coating (ARC) layer is deposited on top of the a-Si triple-stacked layers and is patterned using 10% HCl. The ARC is a transparent, electrically conducting layer and has been designed to improve the light absorption by preventing light reflection from the air/a-Si cell interface. Detailed design considerations for ARC's are available [10], [24]. The a-Si:H is then mesa etched in a 100% carbon tetrafluoride ( $\text{CF}_4$ ) plasma at 150 W incident power. A 1200-Å layer of indium tin oxide (ITO) is deposited using RF sputtering, and is patterned using 5% hydrofluoric acid (HF). The ITO layer is optically transparent and form a series electrical interconnection between individual cells. The sample is then annealed at  $220^\circ\text{C}$  for 20 min. in a rapid thermal processor (RTP) system to decrease the sheet resistance of the ITO. Fig. 4 shows the series interconnected cell array in detail.

## VI. EXPERIMENTS

### A. Triple-Stacked Single-Tandem Cell

Vertically triple-stacked single test cells with area of  $0.1 \text{ cm}^2$  were fabricated as described above and characterized under

near AM 1.5 conditions (the AM 1.5 condition is the standard solar cell test light intensity and energy distribution condition, which corresponds to illuminated sunlight on the surface of the earth when the sun is at an inclination of  $48.19^\circ$  relative to overhead). A typical I-V characteristic curve of single cell is shown in Fig. 5. The  $V_{oc}$  is in the range of  $1.8 \sim 2.3 \text{ V}$ , the short circuit current density  $J_{sc}$  is about  $2.8 \text{ mA/cm}^2$ , and the fill factor (FF) is 0.495. As shown in Fig. 5, the FF is low, in part due to the Cr rear contact, which may diffuse into the a-Si:H active layer during the dc glow-discharge decomposition at  $250^\circ\text{C}$ , resulting in lower FF and lower  $V_{oc}$ . Different metals are planned for use as a rear contact, such as titanium (Ti), to reduce this effect and improve  $V_{oc}$ . The  $J_{sc}$  can be improved further by using an efficient ARC and *i*-layer thickness optimization.

### B. Series-Interconnected Solar Cell Array

After making series interconnection between individual solar cells as described above, the array  $V_{oc}$  was measured under varying light conditions. The array  $V_{oc}$  measurements were carried out using a Keithley 236 Source Measurement Unit, which has a very high input impedance to prevent any voltage drop during the voltage measurement due to loading effects. The array  $V_{oc}$  as a function of the number of cells in series under varying illuminations is shown in Fig. 6. As expected, the array  $V_{oc}$  is linearly proportional to the number of cells in

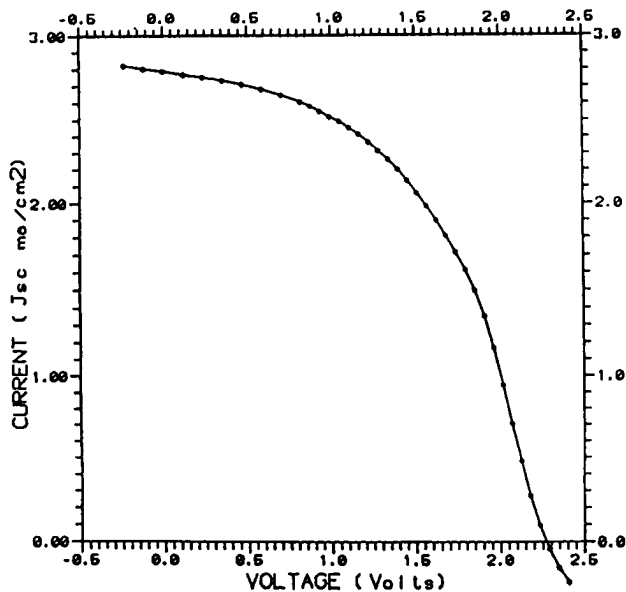


Fig. 5. The I-V characteristic curve for triple-stacked single a-Si:H solar cell.

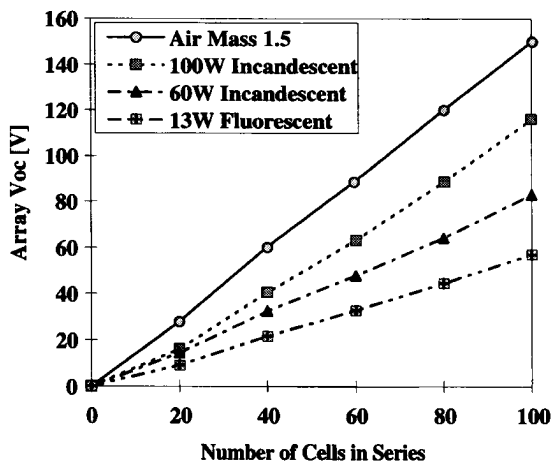


Fig. 6. Array  $V_{oc}$  as a function of number of cells in array, under AM 1.5, 100-W incandescent light bulb/40 cm apart, 60-W incandescent light bulb/40 cm apart, 13-W fluorescent lamp/40 cm apart, respectively.

the array. For a 100-cell series-interconnected array (total array area of  $1 \text{ cm}^2$ ), the measured  $V_{oc}$  is as high as 150 V under AM 1.5 condition. Even under the relatively poor illumination of a 13-W fluorescent lamp, which is located at 40 cm above the cell array, a  $V_{oc}$  of 57 V was attained.

For a 100-cell series-interconnected array (total array area including interconnections of  $1 \text{ cm} \times 1 \text{ cm}$ , and total amorphous silicon area of  $6 \text{ mm} \times 6 \text{ mm}$ ), the measured  $I_{sc}$  is  $2.8 \mu\text{A}$  under AM 1.5 illumination. The sheet resistance of the ITO after annealing is about  $20 \Omega/\text{square}$ . The calculated resistivity of the ITO in the cell array is  $(20 \Omega/\text{square}) * (1200 \text{ \AA}) = 240 \mu\Omega\text{-cm}$ . With this sheet resistance value, the power available from the cell is reduced in the worst case (i.e., maximum current being drawn from the cell) by 12%. At low current values, this efficiency loss is correspondingly reduced.

When the number of series interconnected cells in the array is kept constant, the array  $V_{oc}$  increases as the light intensity increases. The variation of array  $V_{oc}$  as a function of

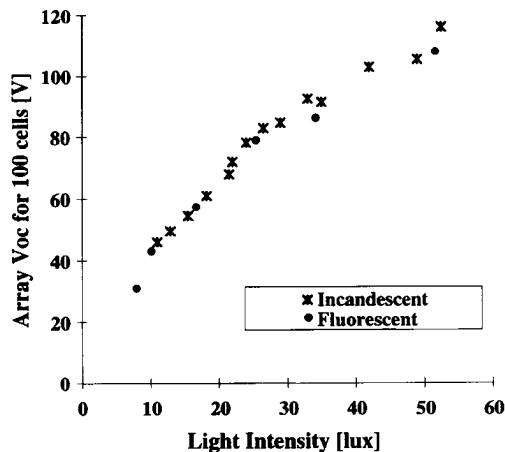
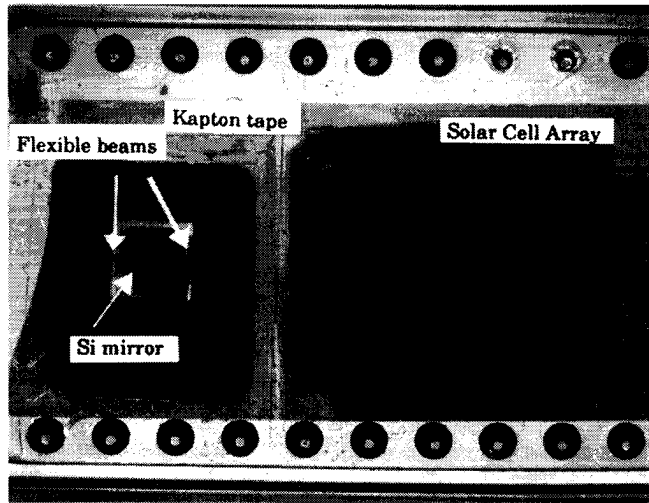


Fig. 7. Array  $V_{oc}$  as a function of photometric light intensity, which has been carried out by varying the distance between light sources and cell array.

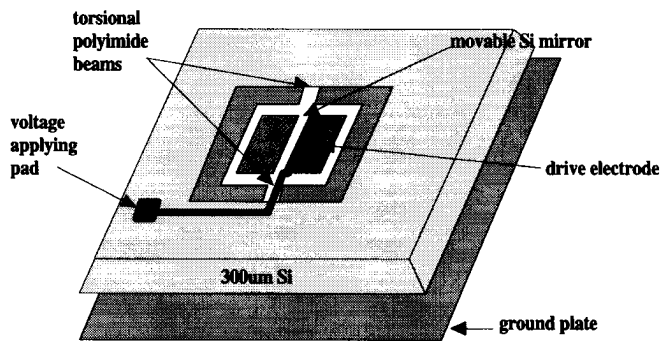
light intensity variation (actually varying the distance between the cell array and the light source) has been measured by using a PASCO 9152B photometer. Fig. 7 shows the resultant  $V_{oc}$  as a function of illuminance (lux) under varying light sources, where 1 lux is equal to  $1 \text{ lm}/\text{m}^2$  at a wavelength of 560 nm [25]. Even though the spectral response of the photometer does not exactly match that of the incandescent and fluorescent lamps, the measured light intensities give relative references. The illumination engineering society recommends that 100 lux for normal lighting in ordinary residences. Based on this recommendation, the 100-cell series-interconnected array can produce above 100 V either under the incandescent lamp or fluorescent lamp in an ordinary residential area. The results described in Figs. 6 and 7 illustrate that the solar cell array developed in this paper is applicable as a high voltage power supply for many electrostatically driven micromachined devices even under ordinary room light conditions.

C. Demonstration of Electrostatic MEMS Operation

The series-interconnected array of one hundred a-Si:H solar cells was bonded and packaged on a standard flat-pack carrier with a micromachined movable Si mirror suspended at its center by flexible polyimide supports [9]. The photomicrograph of the packaged device is shown in Fig. 8(a). The movable Si mirror is directly driven by the electrical output of the solar cell array. The driving voltage from the cell array is placed between the electrode on top of the movable Si mirror plate and the underlying metallic surface (ground) of the flat-pack carrier. A polyimide (Kapton) tape has been placed underneath the suspended Si mirror to prevent electrical shorting between the Si mirror plate and the bottom ground. The deflection of the tip of the Si mirror was measured by focusing on the tip of the mirror using a Nikon MM-11 Measurescope and measuring the deflection of the microscope head necessary to keep the deflecting tip in focus. Motion of the Si mirror plate was observed from approximately 63 V array output. As expected for this type of electrostatically driven capacitive actuator, the deflection of the tip of the mirror is linearly proportional to the square of the output voltage of the cell



(a)



(b)

Fig. 8. (a) A photograph of a series interconnected 100-cell array (total array area of  $1 \text{ cm}^2$ ) packaged with a movable Si mirror. (b) A schematic diagram of the movable Si mirror.

array up to 105 V (where the voltage variation was obtained by varying the position of the light source relative to the cell array), at which time the movable Si mirror plate snapped to the bottom electrode. The detailed plot of the deflection of the tip of the mirror is shown in Fig. 9. This behavior could be reproducibly observed.

## VII. CONCLUSION

An a-Si:H solar cell array with multiple number of cells interconnected in series has been designed, fabricated, characterized, and demonstrated as an on-board power supply for an electrostatically driven micromachined device. The electrical output characteristics of the solar cell array are well matched to the power requirements of electrostatic MEMS. An open circuit voltage as high as 150 V and a short circuit current of  $2.8 \mu\text{A}$  under AM 1.5 conditions has been achieved by this small size ( $1 \text{ cm}^2$ ) solar cell array. Variation of the incident light intensity produces an adjustable array  $V_{oc}$ , thus allowing control of electrostatic actuation by changing the incident light intensity. This solar cell array can also be used as power supply for any device that requires voltages ranging from several to above 100 V with small currents in the  $\text{nA} \sim \mu\text{A}$  range.

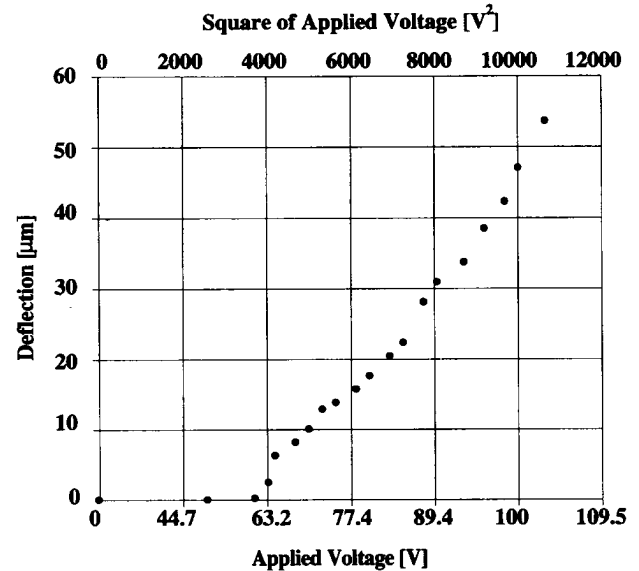


Fig. 9. Deflection of the tip of the Si mirror as a function of square of applied output voltage of an a-Si:H solar cell array.

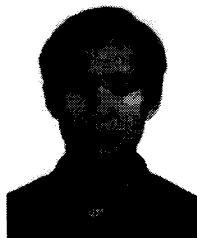
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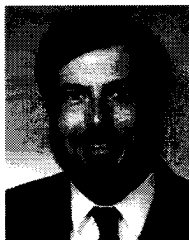


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